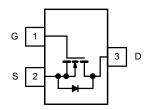


# QM0008K-VB Datasheet N-Channel 100 V (D-S) MOSFET

MOSFET	PRODUCT SUMM	ARY	
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
	0.240 at V <sub>GS</sub> = 10 V	2.0	
100	0.250 at V <sub>GS</sub> = 6 V	1.8	2.9 nC
	0.260 at V <sub>GS</sub> = 4.5 V	1.7	



#### **FEATURES**

- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
  100 % UIS Tested
- Material categorization:



### **APPLICATIONS**

- DC/DC Converters
- Load Switch
- LED Backlighting in LCD TVs

ABSOLUTE MAXIMUM RATINGS (TA	= 25 °C, unless oth	nerwise noted)		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	100	W	
Gate-Source Voltage	$V_{GS}$	± 20	O V V C A A C MJ	
	T <sub>C</sub> = 25 °C		2	
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C		1.8	
Continuous Diam Current (1) = 150°C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	1.6 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		1.3 <sup>b, c</sup>	
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	7	7 ^
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	2.1	
Continuous Source-Diain Diode Current	T <sub>A</sub> = 25 °C		1.0 <sup>b, c</sup>	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	5	
Single Pulse Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>	1.25	mJ
	T <sub>C</sub> = 25 °C	В	2.5	
Maximum Power Dissination	T <sub>C</sub> = 70 °C		1.6	۱۸/
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.25 <sup>b, c</sup>	VV V
	T <sub>A</sub> = 70 °C		0.8 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	R <sub>thJA</sub>	75	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	40	50	- C/VV		

#### Notes:

- a. Based on T<sub>C</sub> = 25 °C.
  b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 166 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static					L	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V, } I_{D} = 250  \mu\text{A}$	100			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			105		>1/06
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	I <sub>D</sub> = 250 μA		- 5.2		mV/°(
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2		2.8	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
7 0 1 1/1 5 1 0 1		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			- 1	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	5			Α
	,	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.5 A		0.240		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 1 A		0.250		Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$		0.260		-
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 1.5 A		2.0		S
Dynamic <sup>b</sup>				II.		
Input Capacitance	C <sub>iss</sub>			190		T .
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		22		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	23 7 GS - 7		13	3	
Treverse Harrison Capacitance		Vps = 50 V. Vcs = 10 V. lp = 1.6 A	os = 50 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.6 A 5.2 10.4			
Total Gate Charge	Qg	103 10 1, 103 10 1, 10 11		2.9	5.8	-
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 1.6 \text{ A}$		0.75		nC
Gate-Drain Charge	Q <sub>gd</sub>	20 7 00 7 2		1.4		1
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.3	1.4	2.8	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			30	45	
Rise Time	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_1 = 39 \Omega$		26	39	1
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = 1.3 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_a = 1 \Omega$		17	26	1
Fall Time	t <sub>f</sub>	g		12	20	-
Turn-On Delay Time	t <sub>d(on)</sub>			6	12	ns
Rise Time	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_1 = 39 \Omega$		10	20	-
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = 1.3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	20	-
Fall Time	t <sub>f</sub>	<u> </u>		6	12	-
Drain-Source Body Diode Characteristi	· ·					
Continuous Source-Drain Diode Current	Is	T <sub>C</sub> = 25 °C			- 2.1	Τ
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	-			- 20	Α
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.3 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			22	33	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			21	32	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 1.3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		16		<u> </u>
Reverse Recovery Rise Time	t <sub>b</sub>			6		ns

#### Notes:

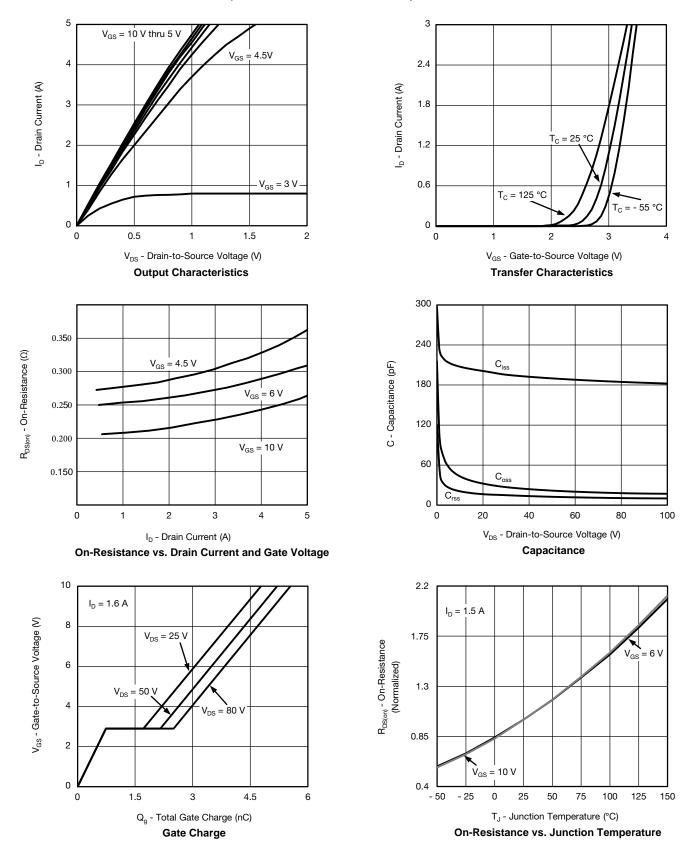
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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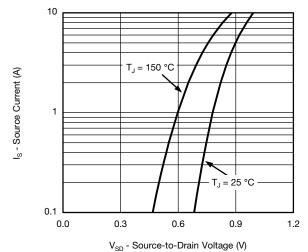


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

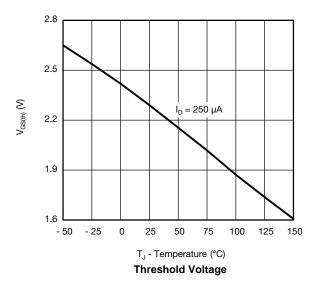


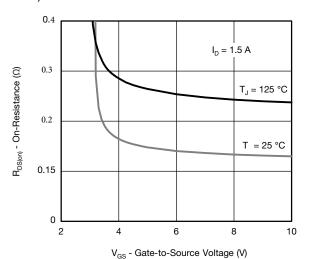


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

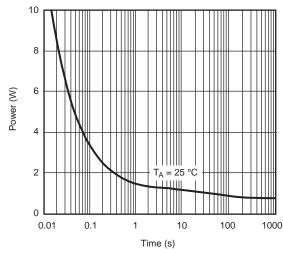


## Source-Drain Diode Forward Voltage

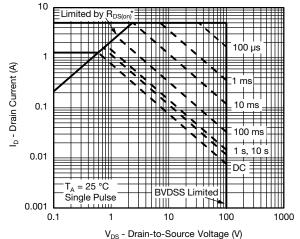




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power

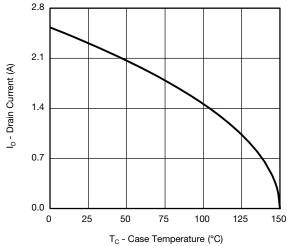


\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

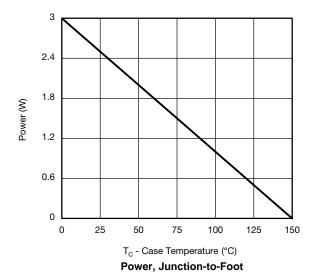
Safe Operating Area

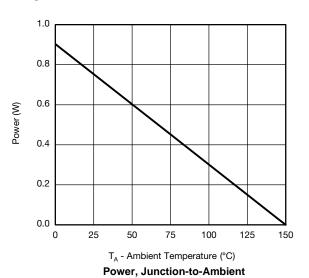


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





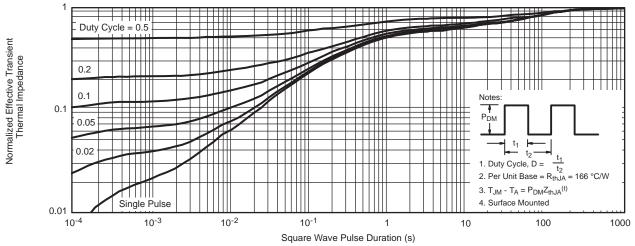




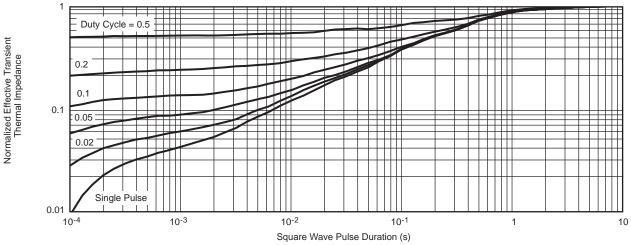
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



#### Normalized Thermal Transient Impedance, Junction-to-Foot

### Note

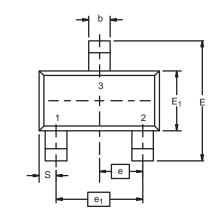
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

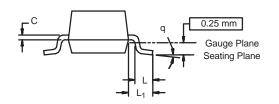
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## SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
Α	0.89	1.12	0.035	0.044
A <sub>1</sub>	0.01	0.10	0.0004	0.004
A <sub>2</sub>	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
С	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E <sub>1</sub>	1.20	1.40	0.047	0.055
е	0.95	0.95 BSC		4 Ref
e <sub>1</sub>	1.90	1.90 BSC		8 Ref
L	0.40	0.60	0.016	0.024
L <sub>1</sub>	0.64 Ref		0.025	5 Ref
S	0.50 Ref		0.020	) Ref
q	3°	8°	3°	8°

DWG: 5479



### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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